Title (en)

Electrolytic copper plating solutions and a method for their application.

Title (de)

Elektrolytische Kupferplattierungslösungen und Verfahren für ihre Anwendung.

Title (fr)

Solutions de dépÔt électrolytique de cuivre et procédé pour leur application.

Publication

EP 0107109 A2 19840502 (EN)

Application

EP 83109814 A 19830930

Priority

US 42905582 A 19820930

Abstract (en)

Acid copper electroplating solutions containing the reaction product of (1) a compound of the formula <CHEM> wherein R1 and R2 are lower alkyl radicals of with 1 to 6 carbon atoms, a hydrogen atom or mixtures thereof and R4 is an alkali metal, hydrogen, magnesium, or the groups SX or SSX, wherein X is an alkali metal, hydrogen or magnesium, or a compound of the formula <CHEM> wherein R3 is an aromatic, heterocyclic or alicyclic radical containing 3 to 12 carbon atoms and R4 is an alkali metal, hydrogen, magnesium, or the groups SX or SSX where X is an alkali metal, hydrogen or magnesium, (2) a compound of the formula XR1-(S)n-R2-SO3H wherein R1 and R2 are the same or different and are alkylene radicals containing 1 to 6 carbon atoms, X is hydrogen or -SO3H and n equals 2 to 5, and (3) acrylamide in a sufficient amount to increase the brightness of the deposit and/or to prevent the formation of cracks during thermal shock.

IPC 1-7

C25D 3/38; C07G 17/00

IPC 8 full level

C07G 17/00 (2006.01); **C07G 99/00** (2009.01); **C25B 11/06** (2006.01); **C25D 3/38** (2006.01)

CPC (source: EP)

C25D 3/38 (2013.01)

Cited by

WO2006094755A1; EP1568802A4; DE4032864A1; DE10337669A1; DE10337669B4; DE19758121A1; DE19758121C2; EP0297306A1; AT396946B; US7771835B2; US8114263B2

Designated contracting state (EPC)

AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)

EP 0107109 A2 19840502; **EP 0107109 A3 19840725**; **EP 0107109 B1 19880224**; AT E32611 T1 19880315; DE 107109 T1 19850214; DE 3375732 D1 19880331; JP S59501829 A 19841101; JP S6250559 B2 19871026; WO 8401393 A1 19840412

DOCDB simple family (application)

EP 83109814 A 19830930; AT 83109814 T 19830930; DE 3375732 T 19830930; DE 83109814 T 19830930; JP 50335183 A 19830928; US 8301508 W 19830928